SMBJ33A

Transient Voltage Suppressors

IFSM: 100A Pppm: 600W



FEATURE

Low profile package Ideal for surface mount pick and place applications **Excellent clamping capability** Very fast response time Low incremental surge resistance Glass passivated chip junction High temperature soldering guaranteed 260°C/10sec/at terminals

MECHANICAL DATA

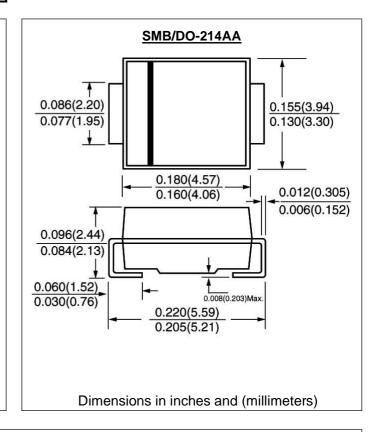
Terminal: Plated axial leads solderable per MIL-STD 202E, method 208C

Case: Molded with UL-94 Class V-0 recognized Flame

Retardant Epoxy

Polarity: color band denotes cathode end

Mounting position: any



MAXIMUM RATINGS (TA = $25 ^{\circ}$ C unless otherwise noted)			
Parameter	Symbol	SMBJ33A	units
Peak pulse power dissipation with a 10/1000 µs waveform ^(1,2) (Fig. 1)	P _{PPM}	600	W
Peak pulse current with a 10/1000 µs waveform (1)	I _{PPM}	11.3	А
Breakdown Voltage at I _T =1mA	V_{BR}	36.7min 40.6max	V
Maximum Reverse Leakage at V _{WM} =33V	I _R	1.0	μA
Maximum Clamping Voltage at IPPM	V _C	53.3	V
Peak forward surge current 8.3 ms single half sine-wave unidirectional only ⁽²⁾	I _{FSM}	100	А
Maximum instantaneous forward voltage at 50A for uni- directional only	V_{F}	3.5	V
Typical thermal resistance, junction-to-lead	Rth(jl)	20	°C/W
Typical thermal resistance, junction-toambient	Rth(ja)	100	€/W
Operating junction and Storage temperature range	Tj,Tstg	-55 to +150	°C

(1) Non-repetitive current pulse, per Fig. 3 and derated above TA = 25 ℃ per Fig. 2

(2) Mounted on 0.2×0.2"(5.0×5.0mm) copper pads to each terminal

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RATINGS AND CHARACTERISTIC CURVES SMBJ33A

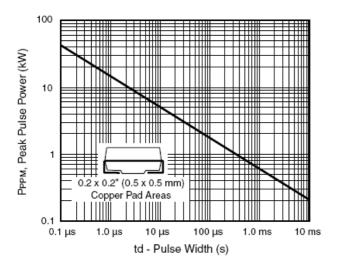


Figure 1. Peak Pulse Power Rating Curve

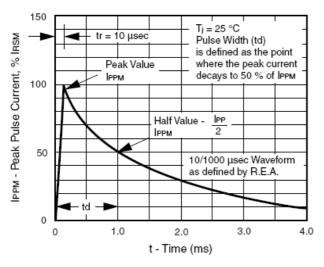


Figure 3. Pulse Waveform

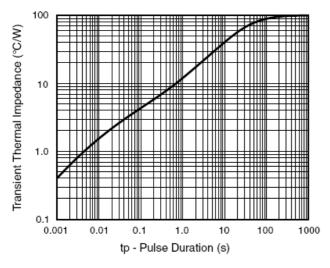


Figure 5. Typical Transient Thermal Impedance

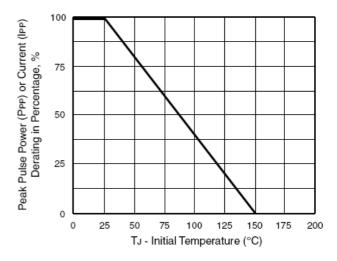


Figure 2. Pulse Power or Current versus Initial Junction Temperature

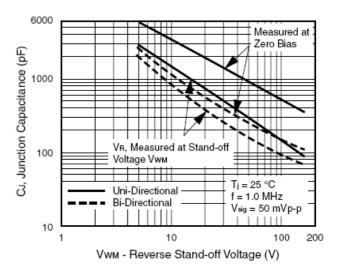


Figure 4. Typical Junction Capacitance

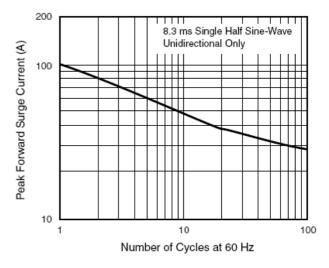


Figure 6. Maximum Non-Repetitive Peak Forward Surge Current

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